3EC-M1S-HTE

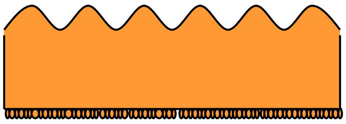
MITSUI
KINZOKU

- 於回火後之高伸率及高耐曲折特性, 等同於壓延銅箔(RA)。
  High Elongation and flexibility after annealing, equally with RA copper foil.
- 於S面微細的表面處理技術、讓3EC-M3S-HTE具更低的處理面粗糙度。
  Lower profile compare with 3EC-M3S-HTE because of S-side surface treatment.

用途/Application

・軟性電路板
/Flexible Print Board

構成/Composition



生產地點/Production Site

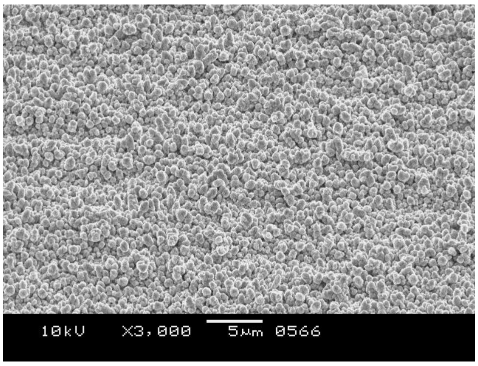
・日本/Japan

代表性特性數據/Representive

	μm	Laminate side Rz(μm)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)@FR-4
3EC-M1S-HTE	9	1.8	390	5	0.6
	12	1.8	390	6	0.7

※上述表列為代表性數據非保証值
This is representative date, not guarantee.

處理面/Laminate side



阻劑面 resist side